

IN THE SPECIFICATION:

Please amend the paragraph beginning on page 48, line 10 as follows:

--As can be understood from FIG. 24, the process for the image sensor 142 is basically the same as that for forming a liquid crystal panel until formation of TFT. Thus, in the embodiment, as in the case of the first embodiment, a conductive film, an insulating film and a semiconductor film are formed to constitute TFT of the display region and the image sensor in the ~~sate~~state of the master glass substrate. Primary cutting is performed to cut the master glass substrate into four sub-TFT substrates. Then, the interlayer substrate 156 made of SiO₂ is formed on the sub-TFT substrate to have a thickness of 0.5 to 1.0 μ m.--

Please amend the paragraph on page 51, line 13 as follows:

--In the case of a liquid crystal panel with a built-in solar battery, a liquid crystal panel with a built-in one-dimensional or two-dimensional tightly fixed image sensor, a liquid crystal panel with a built-in one-dimensional or two-dimensional no-adhesion image sensor, an intelligent panel with a built-in optical communication light sensor or the like, a photoelectric conversion layer is formed on an upper layer portion. Such a liquid crystal panel with a built-in sensor can be efficiently formed by forming a photoelectric conversion layer in a sub-TFT substrate processing process after primary cutting as in the case of the embodiment.

The embodiment can be applied to manufacturing of PC with a built-in two-dimensional image sensor (digital camera) of a non-adhesion type, a portable information equipment having a copying function, which incorporates a line sensor (scanner) or aan adhesive type, or the like.